



60V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Tc = +25°C
60V	2mΩ @ V _{GS} = 10V	205A
	$3.3 \text{m}\Omega @ V_{GS} = 4.5 \text{V}$	165A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

Features

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- Low Rds(ON) Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

 https://www.diodes.com/quality/product-definitions/
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMTH6002LPSWQ)

Mechanical Data

- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (3)

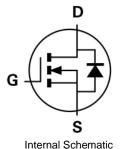
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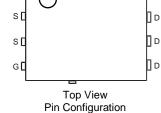
Weight: 0.097 grams (Approximate)



Top View

Bottom View





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Ordering Information (Note 4)

Part Number	Case	Packaging			
DMTH6002LPSW-13	PowerDI5060-8 (SWP) (Standard)	2,500 / Tape & Reel			

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



☐ I = Manufacturer's Marking
TH6002LSW = Product Type Marking Code
YYWW or YYWW = Date Code Marking
YY or YY = Last Two Digits of Year (ex: 21 = 2021)
WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	60	V	
Gate-Source Voltage	Vgss	±20	V	
Continuous Drain Current, V _{GS} = 10V (Note 6) $ T_C = +25^{\circ}C $ $ T_C = +100^{\circ}C $		lo	205 145	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	820	A	
Maximum Continuous Body Diode Forward Current (Note 6) $T_C = +25^{\circ}C$		Is	205	A
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%	Isм	820	А	
Avalanche Current, L = 3mH	I _{AS}	21	A	
Avalanche Energy, L = 3mH	Eas	662	mJ	

Thermal Characteristics

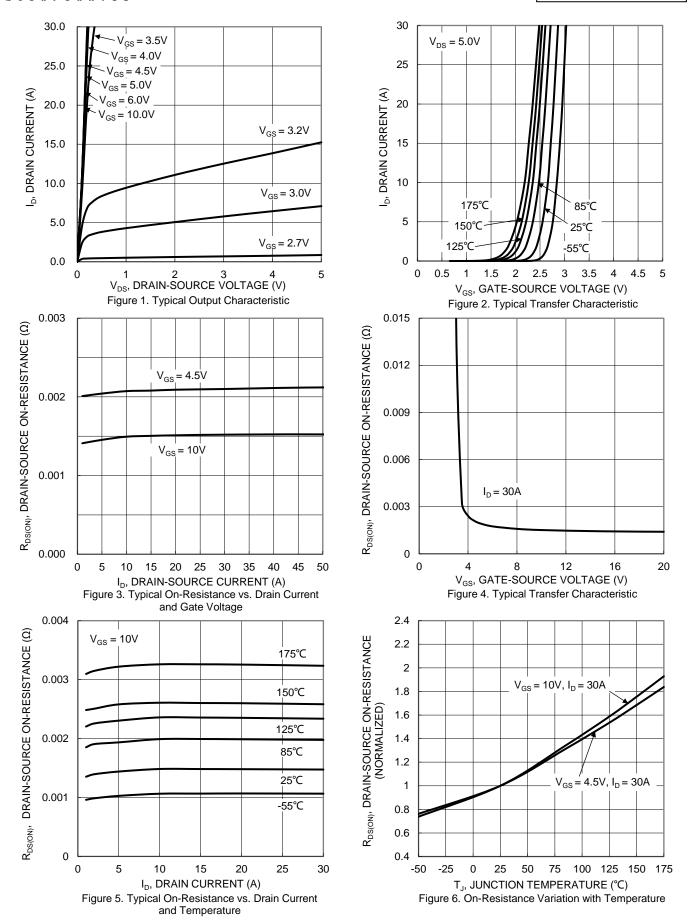
Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _A = +25°C	PD	3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	50	°C/W
Total Power Dissipation (Note 6)	Tc = +25°C	PD	167	W
Thermal Resistance, Junction to Case (Note 6)	R _θ JC	0.9	°C/W	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 48V$, $V_{GS} = 0V$	
Gate-Source Leakage	lgss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1	_	3	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	Process	_	1.5	2	mΩ	$V_{GS} = 10V, I_{D} = 30A$	
Static Drain-Source On-Resistance	RDS(ON)	_	2.1	3.3	11122	$V_{GS} = 4.5V, I_{D} = 30A$	
Diode Forward Voltage	V_{SD}	_	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 30A$	
DYNAMIC CHARACTERISTICS (Note 8)						•	
Input Capacitance	Ciss	_	8289	_		V _{DS} = 30V, V _{GS} = 0V, f = 1MHz	
Output Capacitance	Coss	_	2467	_	pF		
Reverse Transfer Capacitance	Crss	_	179	_			
Gate Resistance	Rg	_	0.76	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	68	_			
Total Gate Charge (V _{GS} = 10V)	Qg	_	131	_	nC	V _{DS} = 30V, I _D = 50A	
Gate-Source Charge	Qgs	_	20.3	_	IIC		
Gate-Drain Charge	Qgd	_	30.5	_			
Turn-On Delay Time	t _{D(ON)}	_	9.8	_		$V_{DD} = 30V, V_{GS} = 10V,$ $I_{D} = 50A, R_{g} = 2.5\Omega$	
Turn-On Rise Time	t _R	_	17.1	_			
Turn-Off Delay Time	t _D (OFF)	_	67.3	_	ns		
Turn-Off Fall Time	t _F	_	32.9	_			
Body Diode Reverse Recovery Time	t _{RR}	_	67	_	ns	I_ 500 di/dt 4000/cc	
Body Diode Reverse Recovery Charge	Qrr	_	141	_	nC	$I_F = 50A$, di/dt = 100A/ μ s	

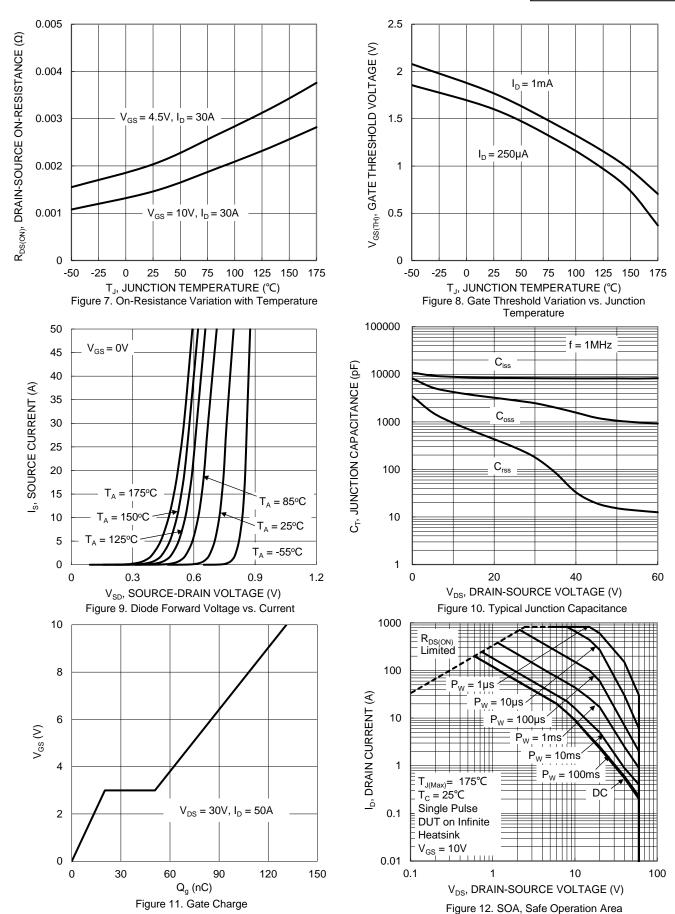
 Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 Thermal resistance from junction to soldering point (on the exposed drain pad).
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:













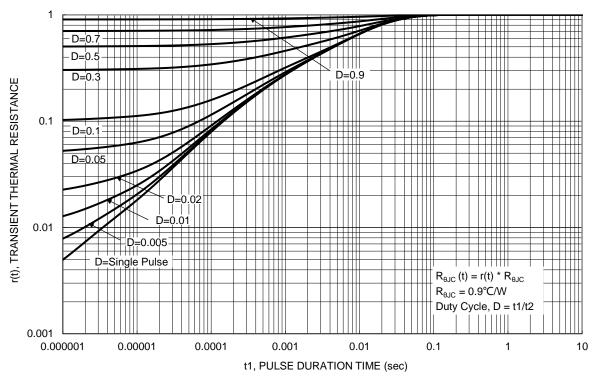


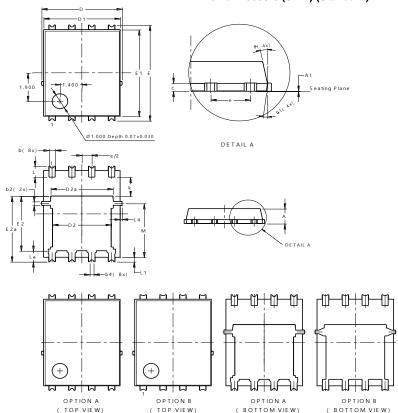
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (SWP) (Standard)

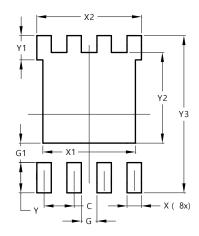


PowerDI5060-8 (SWP) (Standard)				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0	0.05		
b	0.30	0.50	0.41	
b2	0.20	0.35	0.25	
b4	().25REF		
С	0.230	0.330	0.277	
D	5	.15 BS0)	
D1	4.70	5.10	4.90	
D2	3.56	3.96	3.76	
D2a	3.78	4.18	3.98	
Е	6	.40 BS0)	
E1	5.60	6.00	5.80	
E2	3.46	3.86	3.66	
E2a	4.195	4.595	4.395	
е	1	.27BSC)	
k	1.05			
L	0.635	0.835	0.735	
La	0.635	0.835	0.735	
L1	0.200	0.400	0.300	
L4	0.025	0.225	0.125	
M	3.205	4.005	3.605	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (SWP) (Standard)



Dimensions	Value			
Difficitsions	(in mm)			
С	1.270			
G	0.660			
G1	0.820			
X	0.610			
X1	4.100			
X2	4.420			
Υ	1.270			
Y1	1.020			
Y2	3.810			
Y3	6.610			



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